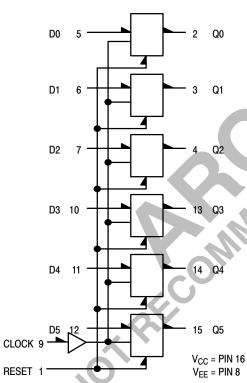
# **Hex D Master-Slave Flip-Flop with Reset**

The MC10186 contains six high–speed, master slave type "D" flip–flops. Clocking is common to all six flip–flops. Data is entered into the master when the clock is low. Master to slave data transfer takes place on the positive–going Clock transition. Thus, outputs may change only on a positive–going Clock transition. A change in the information present at the data (D) input will not affect the output information any other time due to the master–slave construction of this device. A COMMON RESET IS INCLUDED IN THIS CIRCUIT. RESET ONLY FUNCTIONS WHEN CLOCK IS LOW.

## • $P_D = 460 \text{ mW typ/pkg (No Load)}$

- $f_{toggle} = 150 \text{ MHz (typ)}$
- $t_r$ ,  $t_f = 2.0$  ns typ (20%–80%)

#### **LOGIC DIAGRAM**



#### **CLOCKED TRUTH TABLE**

R	С	D	Qn + 1
L	L	Χ	Q <sub>n</sub>
L	H*	┙	L
L	H*	Н	Н
Н	L	Χ	L

<sup>\*</sup>A clock H is a clock transition from a low to a high state.



#### ON Semiconductor

http://onsemi.com



CDIP-16 L SUFFIX CASE 620



**MARKING** 



PDIP-16 P SUFFIX CASE 648





PLCC-20 FN SUFFIX CASE 775

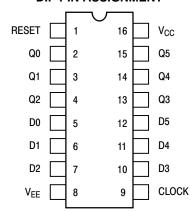


A = Assembly Location

WL = Wafer Lot YY = Year

WW = Work Week

### **DIP PIN ASSIGNMENT**



Pin assignment is for Dual-in-Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).

#### ORDERING INFORMATION

Device	Package	Shipping		
MC10186L	CDIP-16	25 Units / Rail		
MC10186P	PDIP-16	25 Units / Rail		
MC10186FN	PLCC-20	46 Units / Rail		

#### **ELECTRICAL CHARACTERISTICS**

		Pin	Test Limits							
		Under	-30	)∘C		+25°C	1	+85	5°C	
Characteristic	Symbol	Test	Min	Max	Min	Тур	Max	Min	Max	U
Power Supply Drain Current	Ι <sub>Ε</sub>	8		121		88	110		121	m
Input Current	I <sub>inH</sub>	5		350			220		220	μA
		9 1		495 920			310 575		310 575	
		5	0.5	920	0.5		373	0.3	373	μA
Output Voltage Logic 1	I <sub>inL</sub> V <sub>OH</sub>	2†	-1.060	-0.890	-0.960		-0.810	-0.890	-0.700	μr
Output Voltage Logic 1	VOH	15†	-1.060	-0.890	-0.960		-0.810	-0.890	-0.700 -0.700	V
Output Voltage Logic 0	V <sub>OL</sub>	2† 15†	-1.890 -1.890	-1.675 -1.675	-1.850 -1.850		-1.650 -1.650	-1.825 -1.825	-1.615 -1.615	٧
Threshold Voltage Logic 1	V <sub>OHA</sub>	2† 15†	-1.080 -1.080		-0.980 -0.980			-0.910 -0.910		V
Threshold Voltage Logic 0	V <sub>OLA</sub>	2† 15†		-1.655 -1.655			-1.630 -1.630		-1.595 -1.595	٧
Switching Times (50 $\Omega$ Load)										r
Propagation Delay	t <sub>1+3-</sub>	3	1.6	4.6	1.6	2.5	4.5	1.6	5.0	
	t <sub>1+4</sub> _	4 2	1.6 1.6	4.6 4.6	1.6 1.6	2.5 3.5	4.5 4.5	1.6 1.6	5.0 5.0	
	t <sub>9+2+</sub> t <sub>9+2-</sub>	2	1.6	4.6	1.6	3.5	4.5	1.6	5.0	
Rise Time (20 to 80%)	t <sub>2+</sub>	2	1.0	4.1	1.1	1.8	4.0	1.1	4.4	
Fall Time (20 to 80%)	t <sub>2-</sub>	2	1.0	4.1	1.1	1.8	4.0	1.1	4.4	
Setup Time	t <sub>setup</sub>	2	2.5		2.5	2.5		2.5		r
Hold Time	t <sub>hold</sub>	2	1.5		1.5	-1.5		1.5		r
Toggle Frequency (Max)	f <sub>tog</sub>	2	125		125	150		125		М
OFNICE	-									

V<sub>IH</sub> appears at clock input (Pin 9).

### **ELECTRICAL CHARACTERISTICS** (continued)

					TEST VOL	TAGE VALU	JES (Volts)		
		@ Test Te	mperature	V <sub>IHmax</sub>	V <sub>ILmin</sub>	V <sub>IHAmin</sub>	V <sub>ILAmax</sub>	V <sub>EE</sub>	
			–30°C	-0.890	-1.890	-1.205	-1.500	-5.2	
			+25°C	-0.810	-1.850	-1.105	-1.475	-5.2	
			+85°C	-0.700	-1.825	-1.035	-1.440	-5.2	
Pin			TEST V	OLTAGE AP	PLIED TO PI	NS LISTED	BELOW	<i>01</i> )	
Characteris	Characteristic		Under Test	V <sub>IHmax</sub>	V <sub>ILmin</sub>	V <sub>IHAmin</sub>	V <sub>ILAmax</sub>	V <sub>EE</sub>	(V <sub>CC</sub> ) Gnd
Power Supply Drain Co	urrent	ΙE	8					8	16
Input Current		l <sub>inH</sub>	5 9 1	5 9 1				8 8 8	16 16 16
		I <sub>inL</sub>	5		5			8	16
Output Voltage	Logic 1	V <sub>OH</sub>	2† 15†	5 12				8 8	16 16
Output Voltage	Logic 0	V <sub>OL</sub>	2† 15†		5 12			8 8	16 16
Threshold Voltage	Logic 1	V <sub>OHA</sub>	2† 15†			5 12	10.	8 8	16 16
Threshold Voltage	Logic 0	V <sub>OLA</sub>	2† 15†				5 12	8 8	16 16
Switching Times	(50Ω Load)			+1.11Vdc	+0.31V	Pulse In	Pulse Out	-3.2 V	+2.0 V
Propagation Delay		t <sub>1+3</sub> t <sub>1+4</sub> t <sub>9+2+</sub> t <sub>9+2</sub>	3 4 2 2	6 7		1, 9 1, 9 5, 9 5, 9	3 4 2 2	8 8 8	16 16 16 16
Rise Time	(20 to 80%)	t <sub>2+</sub>	2			5, 9	2	8	16
Fall Time	(20 to 80%)	t <sub>2-</sub>	2			5, 9	2	8	16
Setup Time		t <sub>setup</sub>	2			5, 9	2	8	16
Hold Time		t <sub>hold</sub>	2	167		5, 9	2	8	16
Toggle Frequency (Ma	x)	f <sub>tog</sub>	2					8	16

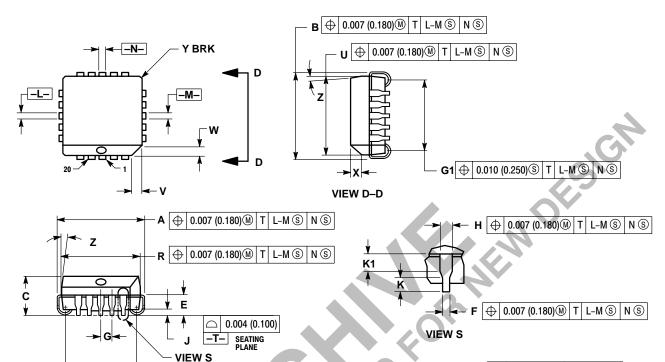
<sup>†</sup> Output level to be measured after clock pulse. ViH appears at clock input (Pin 9).

Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50–ohm resistor to –2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.

#### PACKAGE DIMENSIONS

#### PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



#### NOTES:

G1 ⊕ 0.010 (0.250)③ T L-M ⑤ N ⑤

OF MICE. NOT PERSON

- OTES:

  1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

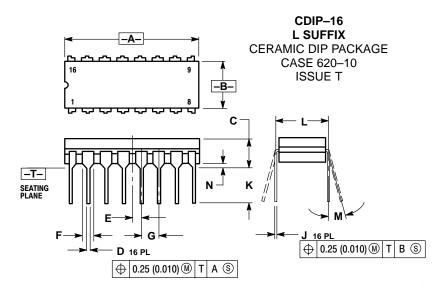
  2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

  3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.

  4. DIMENSIONING AND TOLERANCING PER ANSI V14 5M 1982
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIMETER		
DIM	MIN	MAX	MIN	MAX	
Α	0.385	0.395	9.78	10.03	
В	0.385	0.395	9.78	10.03	
С	0.165	0.180	4.20	4.57	
Ε	0.090	0.110	2.29	2.79	
F	0.013	0.019	0.33	0.48	
G	0.050	BSC	1.27	BSC	
Н	0.026	0.032	0.66	0.81	
J	0.020		0.51		
K	0.025		0.64		
R	0.350	0.356	8.89	9.04	
U	0.350	0.356	8.89	9.04	
٧	0.042	0.048	1.07	1.21	
W	0.042	0.048	1.07	1.21	
X	0.042	0.056	1.07	1.42	
Υ		0.020		0.50	
Z	2°	10°	2°	10 °	
G1	0.310	0.330	7.88	8.38	
K1	0.040		1.02		

#### PACKAGE DIMENSIONS



#### NOTES:

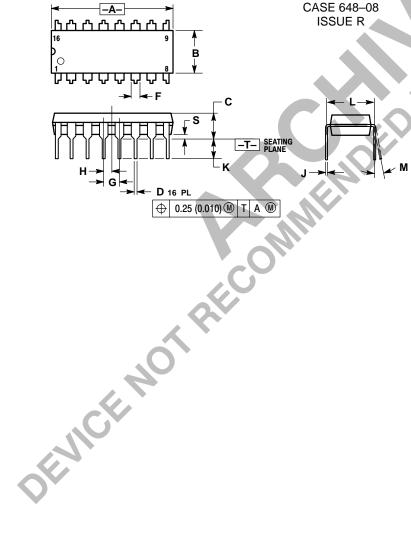
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
   CONTROLLING DIMENSION: INCH.
   DIMENSION LTO CENTER OF LEAD WHEN

- FORMED PARALLEL

  DIMENSION F MAY NARROW TO 0.76 (0.030)
  WHERE THE LEAD ENTERS THE CERAMIC
  BODY.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
С		0.200		5.08	
D	0.015	0.020	0.39	0.50	
E	0.050	BSC	1.27 BSC		
F	0.055	0.065	1.40	1.65	
G	0.100	BSC	2.54 BSC		
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300	BSC	7.62	BSC	
М	0 °	15°	0 °	15°	
N	0.020	0.040	0.51	1.01	

### PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE CASE 648-08 ISSUE R



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
  5. ROUNDED CORNERS OPTIONAL

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27	BSC	
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10°	0°	10 °	
S	0.020	0.040	0.51	1.01	

## **Notes**



## **Notes**





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